2SC1684, 2SC1685

Silicon NPN Epitaxial Planar Type

For general amplification

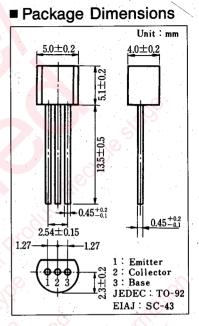
Features

•High DC current gain h_{FE}

•Low collector-emitter saturation voltage $V_{CE(sat)}$

■ Absolute Maximum Ratings (Ta=25°C)

Item		Symbol	Value	Unit
Collector-Base	2SC1684	V	30	V
Voltage	2SC1685	V _{CBO}	60	. •
Collector-Emitter Voltage	2SC1684	V	25	v
	2SC1685	V _{ceo}	50	
Emitter-Base Voltage		V _{EBO}	7.	V
Peak Collector Voltage		I _{CP}	200	mA
Collector Current		Ic	100	mA
Collector Power Dissipation		Pc	400	mW
Junction Temperature		Tj	150	C
Storage Temperature		T _{stg}	- 55 - + 150	3



Electrical Characteristics (Ta=25°C)

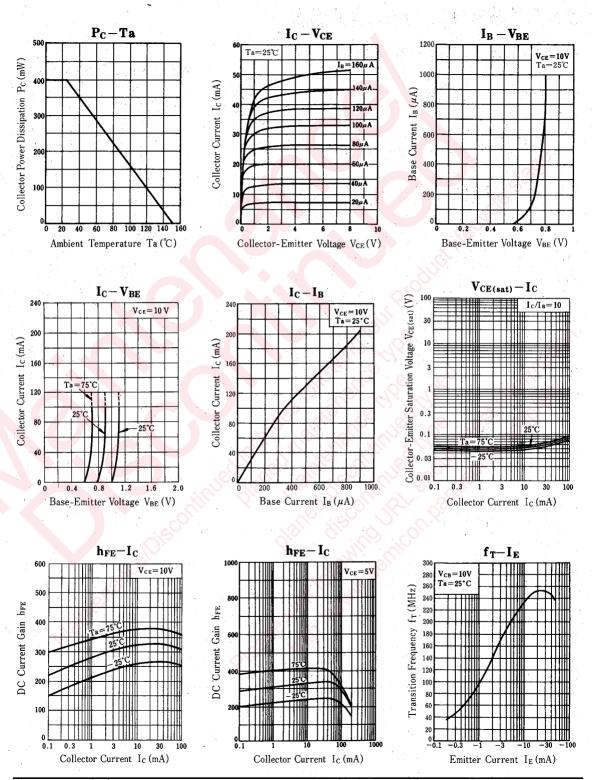
Item		Symbol Condition		min.	typ.	max.	Unit
Collector Cutoff Current		I _{сво}	$V_{cB} = 10 V, I_{E} = 0$			1	μA
		I _{CE0}	$V_{cE} = 10 V, I_{B} = 0$	8	R R	100	μA
Collector-Dase	2SC1684	- V _{сво}	$I_{c} = 10 \ \mu A, \ I_{E} = 0$	30			v
	2SC1685			60			
Collector-Emitter Voltage	2SC1684	V _{CEO}	$I_c = 2 \text{ mA}, I_B = 0$	25			v
	2SC1685			50			
Emitter-Base Voltage		V _{EBO}	$I_{\rm E} = 10 \ \mu {\rm A}, \ I_{\rm C} = 0$	7			V
DC Current Gain		h _{FE1} *	$V_{ce} = 10 V, I_c = 2 mA$	160		460	
		h _{FE2}	$V_{ce} = 2 V, I_c = 100 mA$	90		•	
Collector-Emitter Saturation Voltage V		V _{CE(sat)}	$I_c = 100 \text{ mA}, I_B = 10 \text{ mA}$		0.3	0.5	V ,
Transition Frequency		f _T	$V_{CB}=10V, I_{E}=-2mA, f=200MHz$		150		MHz
Noise Voltage		NV	$V_{cE} = 10 V$, $I_c = 1 mA$, $G_v = 80 dB$ $R_g = 100 k\Omega$, Function = FLAT		300		mV
Collector Output Capacitance		Соь	$V_{CB} = 10 V, I_E = 0, f = 1 MHz$		3.5		pF

* h_{FE1} Ranking

Rank	Q	R	S
h _{FE1}	$160 \sim 260$	200~340	290~460

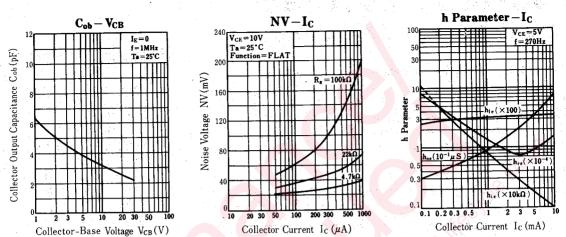
Transistors

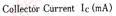
2SC1684, 2SC1685



Transistors

2SC1684, 2SC1685





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